



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Yoshino, et al.

Docket No.: TI-29448

Serial No.: 09/909,013

Examiner: Geyer, Scott

Filed: 07/19/2001

Art Unit: 2829

For: Semiconductor Package Insulation Film and  
Manufacturing Method Thereof

Conf. No.: 8724

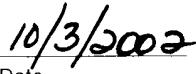
TRANSMITTAL OF FORMAL DRAWINGS

Assistant Commissioner For Patents  
Attn: Official Drafts Person  
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner For Patents, Washington, DC 20231.

  
Elizabeth Austin

  
Date

Dear Sir:

Submitted herewith are 8 sheets of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional fee is necessary.

Respectfully submitted,



Michael K. Skrehot  
Attorney for Applicants  
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